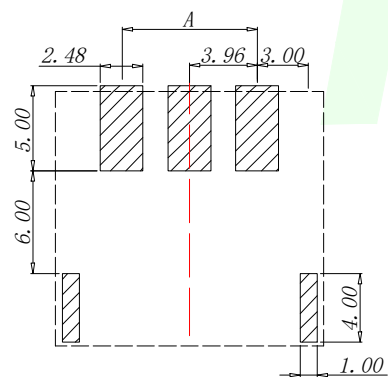
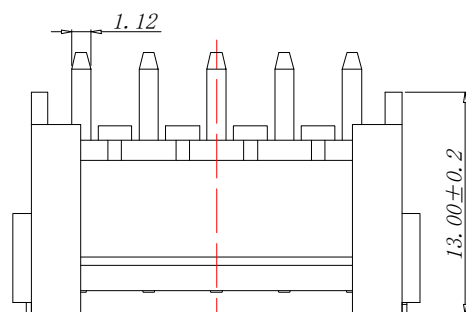
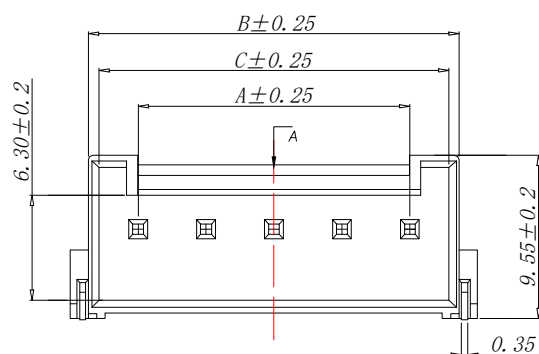
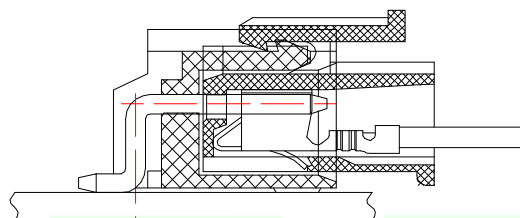


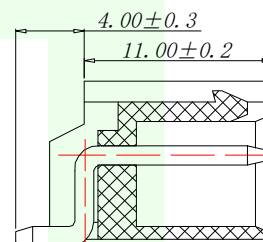
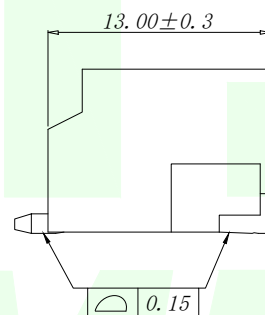
<i>VER</i>	<i>MARK</i>	<i>PR. BY</i>	<i>DESCRIPTION</i>	<i>DATE</i>



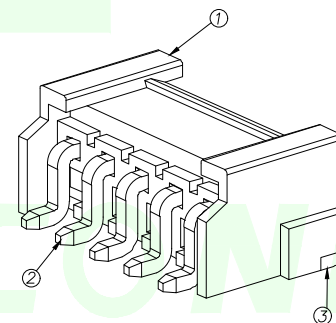
SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



SECTION A-A



PIN number variable size comparison table

PART NO	PIN	A	B	C
HMT-VH3. 96-WT2P	2	3. 96	9. 80	8. 60
HMT-VH3. 96-WT3P	3	7. 92	13. 76	12. 56
HMT-VH3. 96-WT4P	4	11. 88	17. 72	16. 52
HMT-VH3. 96-WT5P	5	15. 84	21. 68	20. 48
HMT-VH3. 96-WT6P	6	19. 80	25. 64	24. 44
HMT-VH3. 96-WT7P	7	23. 76	29. 60	28. 40
HMT-VH3. 96-WT8P	8	27. 72	33. 56	32. 36
HMT-VH3. 96-WT9P	9	31. 68	37. 52	36. 32
HMT-VH3. 96-WT10P	10	35. 64	45. 44	40. 28

技术要求:

1. 塑件材料:LCP(UL-94V-0)
2. 接触件:黄铜镀锡
3. 接触电阻: $\leq 30\text{m}\Omega$
4. 绝缘电阻: $\geq 1000\text{M}\Omega$
5. 额定电压:250V AC DC
6. 额定电流:7.0A AC DC
7. 耐压:能承受1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验:浸锡面积 $\geq 95\%$ 温度260, 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求.

3	焊片 Fitting Nail	黄铜	2	电镀(锡):整个表面 电镀底镍 30u"MIN, 再镀锡 80u"MIN
2	端子 Contact	黄铜	N*1	电镀(锡):整个表面 电镀底镍 30u"MIN, 再镀锡 80u"MIN
1	基座 Wafer	LCP (UL94V-0)	1	米色
序号	名称	材料	数量	备注

GENERAL TOLERANCES UNLESS SPECIFIED		 深圳市华明通电子有限公司 Shenzhen Huamingtong Electronics Co., Ltd			
X.X ±0.30	X.° ±5°	PART NO.		TITLE:	
.XX ±0.20	X.X° ±1°	HMT-VH3.96-WTNP		3.96MM 卧贴	
.XXX ±0.10	X.XX° ±0.5°	DESIGN: James	CUSTOMER	SIZE A4	UNITS MM
MANUFACTURE DWG		CHED: Talen		SCALE	SHEET
		APPD: Sophia		N:A	1/1